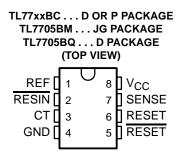
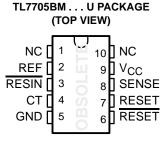
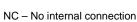
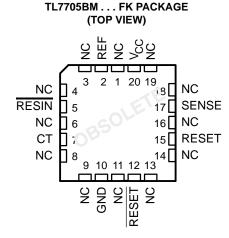
- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- RESET Output Defined From V_{CC} ≥ 1 V
- Precision Voltage Sensor

- Temperature-Compensated Voltage Reference
- True and Complement Reset Outputs
- Externally Adjustable Pulse Duration









NC - No internal connection

description/ordering information

The TL7702B, TL7705B, and TL7733B are integrated-circuit supply-voltage supervisors designed for use as reset controllers in microcomputer and microprocessor systems. The supply-voltage supervisor monitors the supply for undervoltage conditions at the SENSE input. During power up, the \overline{RESET} output becomes active (low) when V_{CC} attains a value approaching 1 V. As V_{CC} approaches 3 V (assuming that SENSE is above V_{T+}), the delay-timer function activates a time delay, after which outputs \overline{RESET} and RESET go inactive (high and low, respectively). When an undervoltage condition occurs during normal operation, outputs \overline{RESET} and RESET go active. To ensure that a complete reset occurs, the reset outputs remain active for a time delay after the voltage at the SENSE input exceeds the positive-going threshold value. The time delay is determined by the value of the external capacitor C_T : $t_d \approx 2.6 \times 10^4 \times C_T$, where C_T is in farads (F) and t_d is in seconds (s).

An external capacitor (typically 0.1 μ F) must be connected to REF to reduce the influence of fast transients in the supply voltage.

The TL7702BC, TL7705BC, and TL7733BC are characterized for operation from 0°C to 70°C. The TL7702BI, TL7705BI, and TL7733BI are characterized for operation from –40°C to 85°C. The TL7705BQ is characterized for operation from –40°C to 125°C. The TL7705BM is characterized for operation from –55°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



description/ordering information (continued)

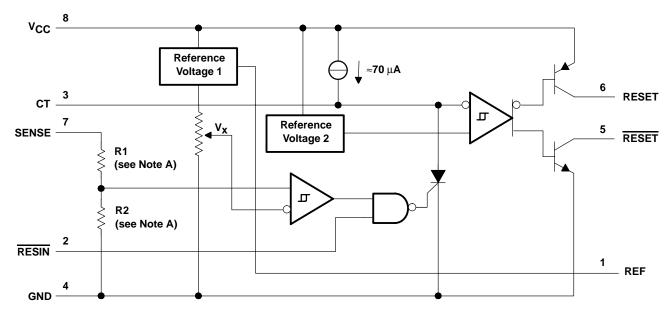
ORDERING INFORMATION

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE Marking
	PDIP (P)	Tube of 50	TL7702BCP	TL7702BCP
	SOIC (D)	Tube of 75	TL7702BCD	7702BC
	SOIC (D)	Reel of 2500	TL7702BCDR	7702BC
	PDIP (P)	Tube of 50	TL7705BCP	TL7705BCP
0°C to 70°C	SOIC (D)	Tube of 75	TL7705BCD	7705BC
	SOIC (D)	Reel of 2500	TL7705BCDR	7705BC
	PDIP (P)	Tube of 50	TL7733BCP	TL7733BCP
	SOIC (D)	Tube of 75	TL7733BCD	7733BC
	301C (D)	Reel of 2500	TL7733BCDR	7733BC
	PDIP (P)	Tube of 50	TL7702BIP	TL7702BIP
	SOIC (D)	Tube of 75	TL7702BID	7702BI
	3010 (D)	Reel of 2500	TL7702BIDR	770261
	PDIP (P)	Tube of 50	TL7705BIP	TL7705BIP
-40°C to 85°C	SOIC (D)	Tube of 75	TL7705BID	7705BI
	3010 (D)	Reel of 2500	TL7705BIDR	770001
	PDIP (P)	Tube of 50	TL7733BIP	TL7705BIP
	SOIC (D)	Tube of 75	TL7733BID	7733BI
	3010 (D)	Reel of 2500	TL7733BIDR	1133DI
-40°C to 125°C	SOIC (D)	Tube of 75	TL7705BQD	TL7705BQD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

functional block diagram

The functional block diagram is shown for illustrative purposes only; the actual circuit includes a trimming network to adjust the reference voltage and sense-comparator trip point.



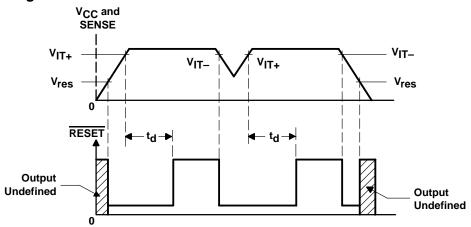
Pin numbers shown are for the D, JG, and P packages.

NOTE A: TL7702B: R1 = 0 Ω , R2 = open, $V_X = V_{REF1}$

TL7705B: R1 = 23 k Ω , R2 = 10 k Ω , nominal, $V_X \approx 1.43 \text{ V}$

TL7733B: R1 = 11.3 k Ω , R2 = 10 k Ω , nominal, $V_X \approx 1.43$ V

typical timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	20 V
Input voltage range, V _I : RESIN	
SENSE	0.3 V to 20 V
High-level output current, IOH (RESET)	–30 mA
Low-level output current, IOL (RESET)	30 mA
Package thermal impedance, θ _{JA} (see Notes 2 and 3):D package	97°C/W
P package	85°C/W
Operating virtual junction temperature, T _J	150°C
Case temperature for 60 seconds, T _C : FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: JG or U packages	300°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or P packages	260°C
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the network ground terminal.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
Vcc	Supply voltage		3.6	18	V
VIH	High-level input voltage RESI	N	2	18	V
V_{IL}	Low-level input voltage RESI	N	0	0.8	V
VI	Input voltage SENS	SE	0	18	V
ЮН	High-level output current RESE	ΕT		-20	mA
loL	Low-level output current RESE	ĒΤ		20	mA
	TL77.	xxBC	0	70	
l .	Operating free pir temperature range	xxBl	-40	85	°C
TA	Operating free-air temperature range	05BQ	-40	125	
	TL77	-55	125		

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST COND	TL77xxBC TL77xxBI TL7705BQ			UNIT			
						MIN	TYP	MAX		
Vон	High-level output vo	oltage, RES	ET	$I_{OH} = -16 \text{ mA}$		V _{CC} -1.5			V	
VOL	Low-level output vo	ltage, RES	ET	I _{OL} = 16 mA				0.4	V	
V _{ref}	Reference voltage,	REF		$I_{ref} = -500 \mu A$,	$T_A = 25^{\circ}C$	2.48	2.53	2.58	V	
			TL7702B			2.505	2.53	2.555		
			TL7705B	T _A = 25°C		4.5	4.55	4.6		
	Negative-going		TL7733B	1		3.03	3.08	3.13] ,	
VIT−	V _{IT} input threshold voltage at SENSE input	age	TL7702B			2.48	2.53	2.58	V	
			TL7705B	T _A = full range‡		4.45	4.55	4.65		
			TL7733B	1	3	3.08	3.16			
			TL7702B				10			
V _{hys}	Hysteresis, SENSE (V _{IT+} – V _{IT} –)		TL7705B	$V_{CC} = 3.6 \text{ V to } 18 \text{ V},$	$T_A = 25^{\circ}C$		30		mV	
	(V + - V -)	TL7		1			10			
V _{res} §	Power-up reset vol	tage		I _{OL} at RESET = 2 mA,	T _A = 25°C			1	V	
	In and account	RESIN		$V_I = 0.4 \text{ V to V}_{CC}$				-10		
"	II Input current		TL7702B	V _I = V _{ref} to 18 V			-0.1	-2	μΑ	
ЮН	High-level output current, RESET		V _O = 18 V,	See Figure 1			50	μΑ		
lOL	OL Low-level output current, RESET		$V_O = 0 V$	See Figure 1			-50	μΑ		
1	Cumply ourrent			V _{SENSE} = 15 V,	RESIN ≥ 2 V		1.8	3	A	
lcc	Supply current			V _{CC} = 18 V,	T _A = full range [‡]			3.5	mA	

switching characteristics, $V_{CC} = 5 \text{ V}$, C_T open, $T_A = 25^{\circ}C$

PARAMETER		PARAMETER FROM (INPUT)		TEST CONDITIONS	TL77xxBC TL77xxBI TL7705BQ			UNIT	
					MIN	TYP	MAX		
tPLH	Propagation delay time from low- to high-level output	RESIN	RESET	See Figures 1, 2, and 3		270	500	ns	
tPHL	Propagation delay time from high- to low-level output	RESIN	RESET	See Figures 1, 2, and 3		270	500	ns	
	Effective pulse duration	RESIN		Soo Figure 2		150		no	
t _W	Effective pulse duration	SENSE		See Figure 2		100			ns
t _r	Rise time		DECET	Con Figures 1 and 2			75	no	
tf	Fall time		RESET	See Figures 1 and 3		150	200	ns	
t _r	Rise time		RESET	See Figures 1 and 3		75	150	no	
t _f	Fall time		RESET	See Figures 1 and 3			50	ns	

[†] All electrical characteristics are measured with 0.1-μF capacitors connected at REF, CT, and V_{CC} to GND.
‡ Full range is 0°C to 70°C for the C-suffix devices, –40°C to 85°C for the I-suffix devices, and –40°C to 125°C for the Q-suffix device.
§ This is the lowest voltage at which RESET becomes active.

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			unizionis†	TL7	705BM		UNIT		
		lesi coi	TEST CONDITIONST			MAX	ONII		
Vон	High-level outpu	ut voltage, F	RESET	I _{OH} = -16 mA		V _{CC} -1.5			V
VOL	Low-level outpu	t voltage, R	ESET	I _{OL} = 16 mA				0.4	V
V _{ref}	Reference volta	ge, REF		$I_{ref} = -500 \mu A$,	T _A = 25°C	2.48	2.53	2.58	V
			TL7702B	T 25°C		2.505	2.53	2.555	
\ \/	Negative-going		TL7705B	T _A = 25°C		4.5	4.55	4.6	V
VIT-	V _{IT} input threshold v at SENSE input	•	TL7702B	T 5500 4 40500		2.48	2.53	2.58	v
				$T_A = -55^{\circ}C$ to 125°C		4.45	4.55	4.65	
\/.	Hysteresis, SEN	NSE	TL7702B	V _{CC} = 3.6 V to 18 V, T _A = 25°C			10		mV
V _{hys}	$(V_{\text{IT+}} - V_{\text{IT-}})$	TL7705B	TL7705B	VCC = 3.6 V to 16 V,		30		IIIV	
v _{res} ‡	Power-up reset	voltage		I_{OL} at $\overline{RESET} = 2 \text{ mA}$,	T _A = 25°C			1	V
l .	Input ourrent	RESIN		$V_I = 0.4 \text{ V to } V_{CC}$				-10	
l _l	Input current	SENSE	TL7702B	$V_I = V_{ref}$ to $V_{CC} - 1.5$	/		-0.1	-2	μΑ
IOH High-level output current, RESET		V _O = 18 V				50	μΑ		
l _{OL}	IOL Low-level output current, RESET		V _O = 0				-50	μΑ	
loo	Supply current		V _{SENSE} = 15 V,	RESIN ≥ 2 V		1.8	3	mΛ	
Icc			V _{CC} = 18 V,	$T_A = -55^{\circ}C$ to $125^{\circ}C$			4	mA	

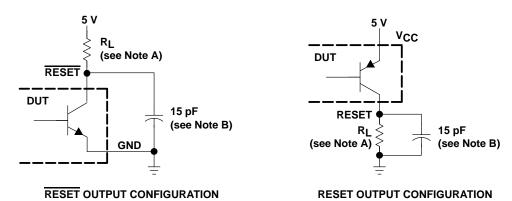
[†] All electrical characteristics are measured with 0.1-μF capacitors connected at REF, CT, and V_{CC} to GND. ‡ This is the lowest value at which RESET becomes active.

switching characteristics, V_{CC} = 5 V, C_T open, T_A = 25°C

	PARAMETER	FROM	то	TEST CONDITIONS	TL	UNIT		
FARAIVIETER		(INPUT) (OUTPUT		1EST CONDITIONS	MIN	TYP	MAX	UNII
tPLH	Propagation delay time from low- to high-level output	RESIN	RESET	See Figures 1, 2, and 3		270	500*	ns
tPHL	Propagation delay time from high- to low-level output	RESIN	RESET	See Figures 1, 2, and 3		270	500*	ns
	Effective pulse duration	RESIN		Coo Figure 2	150			
t _W	Effective pulse duration	SENSE		See Figure 2		100		ns
t _r	Rise time		DECET	See Figures 1 and 3			75*	20
t _f	Fall time		RESET	See rigules 1 and 3		150	200*	ns
t _r	Rise time		RESET	See Figures 1 and 3		75	150*	ne
t _f	Fall time		KESEI	See Figures 1 and 3			50*	ns

^{*} On products compliant to MIL-PRF-38535, these parameters are not production tested.

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. For I_{OL} and I_{OH} , R_L = 10 k Ω . For all switching characteristics, R_L = 511 Ω . B. This figure includes jig and probe capacitance.

Figure 1. RESET and RESET Output Configurations



Figure 2. Input Pulse Definition

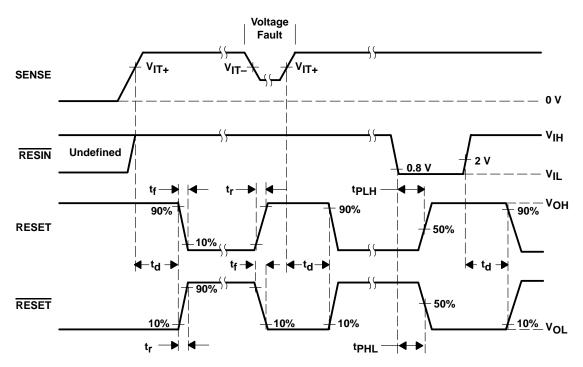
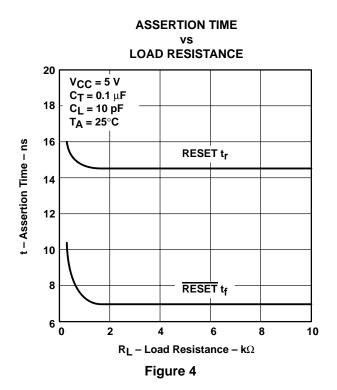
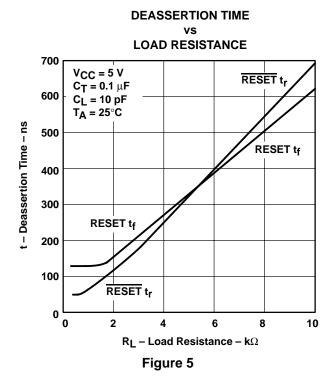
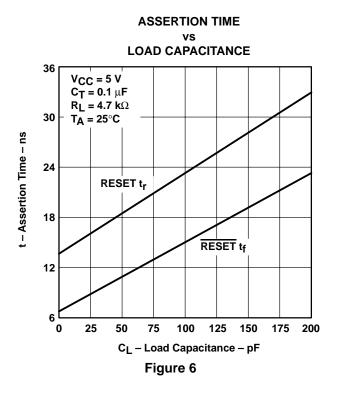


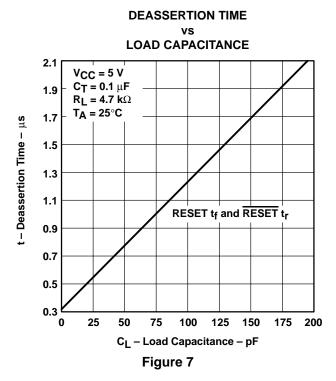
Figure 3. Voltage Waveforms

TYPICAL CHARACTERISTICS[†]









[†] For proper operation, both RESET and RESET should be terminated with resistors of similar value. Failure to do so may cause unwanted plateauing in either output waveform during switching.



APPLICATION INFORMATION

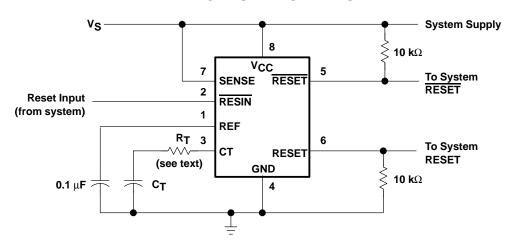


Figure 8. System Reset Controller With Undervoltage Sensing

When the TL770xB SENSE terminal is used to monitor V_{CC}, a current-limiting resistor in series with C_T is recommended. During normal operation, the timing capacitor is charged by the onboard current source to approximately V_{CC} or an internal voltage clamp (≈7.1-V Zener), whichever is less. When the circuit then is subjected to an undervoltage condition during which V_{CC} is rapidly slewed down, the voltage on CT exceeds that on V_{CC} . This forward biases a secondary path internally, which falsely activates the outputs. A fault is indicated when V_{CC} drops below V_(CT), not when V_{SENSE} falls below V_T...

Texas Instruments performs a 100% electrical screen to verify that the outputs do not switch with 1 mA forced into the CT terminal. Adding the external resistor, R_T, prevents false triggering. Its value is calculated as follows:

$$\frac{V_{(CT)}-V_{T_{-}}}{R_{\tau}}$$

 $V_{(CT)} = V_{CC}$ or 7.1 V, whichever is less $V_{T-} = 4.55$ V (nom)

= value of series resistor required

For $V_{CC} = 5 \text{ V}$:

$$\frac{5\,-\,4.55}{R_{\scriptscriptstyle T}} \;<\; 1\;\, mA$$

Therefore,

$$R_{\scriptscriptstyle T}$$
 > 450 Ω

Using a 20%-tolerance resistor, R_T should be greater than 560 Ω .

Adding this series resistor changes the duration of the reset pulse by no more than 10%. R_T extends the discharge of C_T , but also skews the $V_{(CT)}$ threshold. These effects tend to cancel one another. The precise percentage change can be derived theoretically, but the equation is complicated by this interaction and is dependent upon the duration of the supply-voltage fault condition.

Both outputs of the TL770xB should be terminated with similar value resistors, even when only one is being used. This prevents unwanted plateauing in either output waveform during switching, which may be interpreted as an undefined state or delay system reset.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-88685042A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-8868504HA	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI
5962-88685052A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-8868505HA	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI
5962-8868505PA	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7702BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7702BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7702BCP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7702BCPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7702BID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702BIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702BIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702BIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702BIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7702BIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7702BMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7702BMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7702BMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7702BMUB	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI
TL7702BQD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7702BQDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7702BQP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL7705BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BCP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7705BCPE4	ACTIVE	PDIP	Р	8	50	Pb-Free	CU NIPDAU	Level-NC-NC-NC





21-Jun-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
TL7705BID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7705BIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7705BIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7705BMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7705BMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7705BMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7705BMUB	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI
TL7705BQD	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
TL7705BQDR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
TL7705BQP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL7733BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BCP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7733BCPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7733BID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL7733BIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL7733BIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.



PACKAGE OPTION ADDENDUM

21-Jun-2005

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

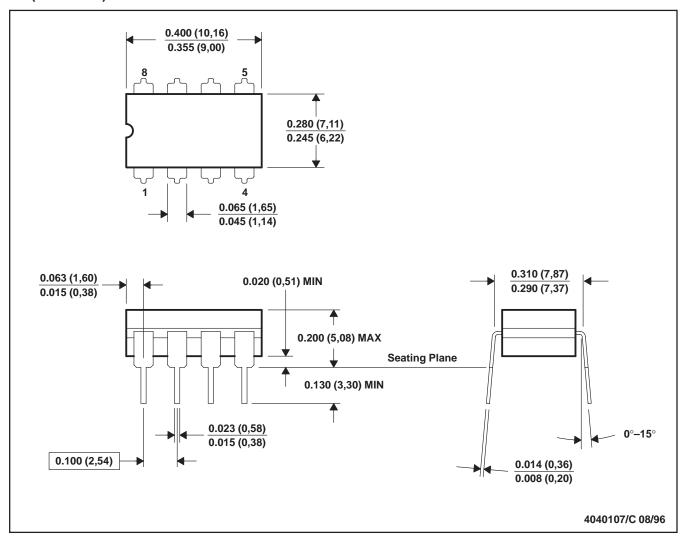
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE

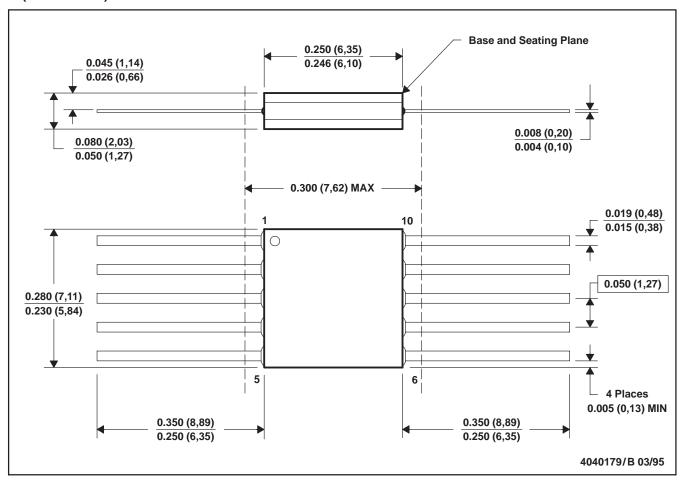


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



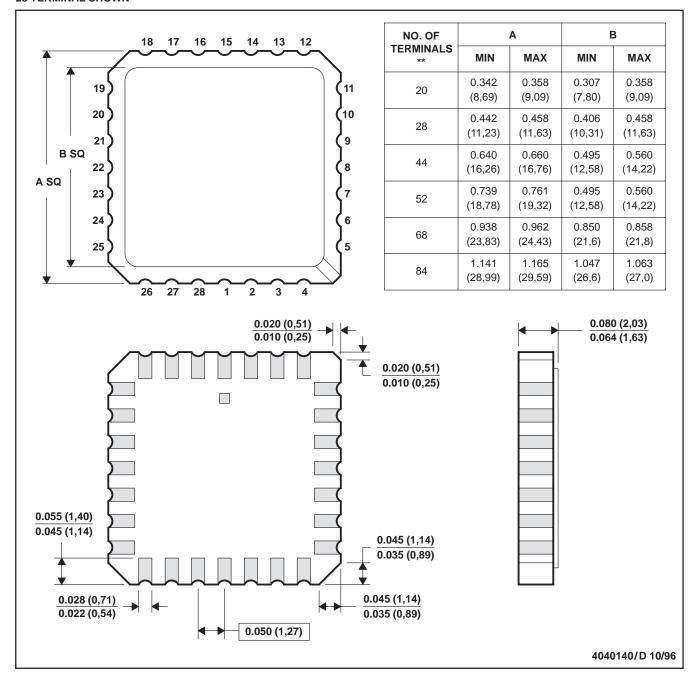
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



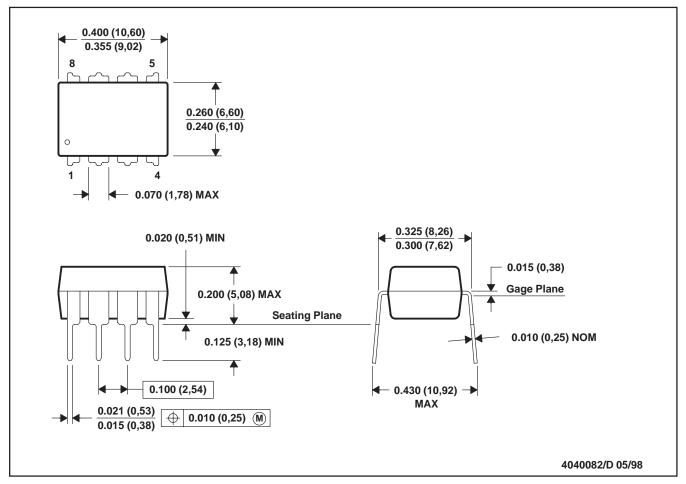
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



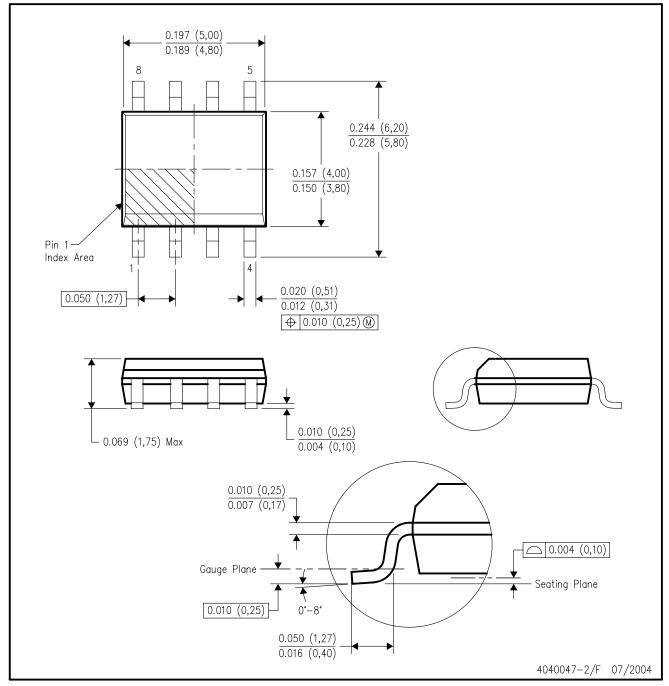
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



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